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#### SN74FB1653 17-BIT LVTTL/BTL UNIVERSAL STORAGE TRANSCEIVER WITH BUFFERED CLOCK LINE SCBS702H – AUGUST 1997 – REVISED MARCH 2004

## description/ordering information

The SN74FB1653 contains an 8-bit and a 9-bit transceiver with a buffered clock. The clock and transceivers are designed to translate signals between LVTTL and BTL environments. The device is designed specifically to be compatible with IEEE Std 1194.1-1991 (BTL).

The A port operates at LVTTL signal levels. The A outputs reflect the inverse of the data at the  $\overline{B}$  port when the A-port output enable (OEA) is high. When OEA is low or when V<sub>CC</sub>(5 V) typically is less than 2.5 V, the A outputs are in the high-impedance state.

The  $\overline{B}$  port operates at BTL signal levels. The open-collector  $\overline{B}$  ports are specified to sink 100 mA. Two output enables (OEB and  $\overline{OEB}$ ) are provided for the  $\overline{B}$  outputs. When OEB is low,  $\overline{OEB}$  is high, or V<sub>CC</sub>(5 V) typically is less than 2.5 V, the  $\overline{B}$  port is turned off.

The clock-select (2SEL1 and 2SEL2) inputs are used to configure the TTL-to-BTL clock paths and delays (refer to the *MUX-MODE DELAY* table).

BIAS  $V_{CC}$  establishes a voltage between 1.62 V and 2.1 V on the BTL outputs when  $V_{CC}(5 V)$  is not connected.

BG V<sub>CC</sub> and BG GND are the supply inputs for the bias generator.

 $V_{REF}$  is an internally generated voltage source. It is recommended that  $V_{REF}$  be decoupled with an external 0.1- $\mu$ F capacitor.

Enhanced heat-dissipation techniques should be used when operating this device from AI to A0 at frequencies greater than 50 MHz, or from AI to  $\overline{B}$  or  $\overline{B}$  to A0 at frequencies greater than 100 MHz.

TA	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	TQFP – PCA	Tube	SN74FB1653PCA	FB1653	

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

#### **Function Tables**

#### TRANSCEIVER

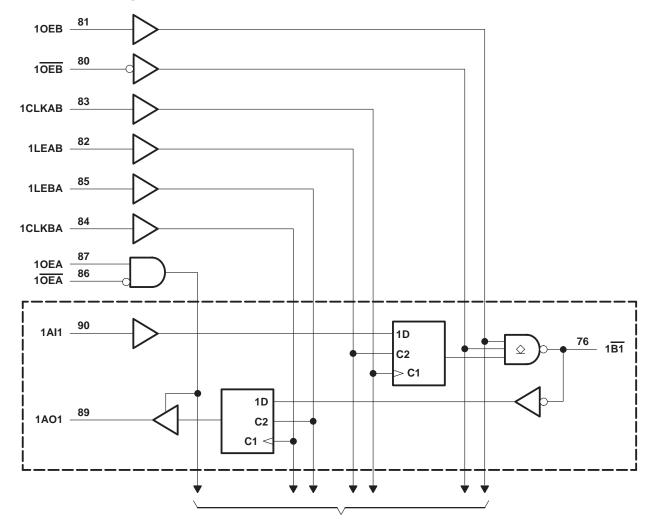
	INP	UTS		FUNCTION	
OEA	OEA	OEB	OEB	FUNCTION	
Х	Х	Н	L	A data to B bus	
L	Н	Х	Х	B data to A bus	
L	Н	Н	L	$\overline{A}$ data to B bus, $\overline{B}$ data to A bus	
Х	Х	L	Х	D has indefen	
Х	Х	Х	н	B-bus isolation	
Н	Х	Х	Х	A-bus isolation	
Х	L	Х	Х		

#### STORAGE MODE

INP	UTS	FUNCTION
LE	CLK	FUNCTION
Н	Х	Transparent
L	Ŷ	Store data
L	L	Storage



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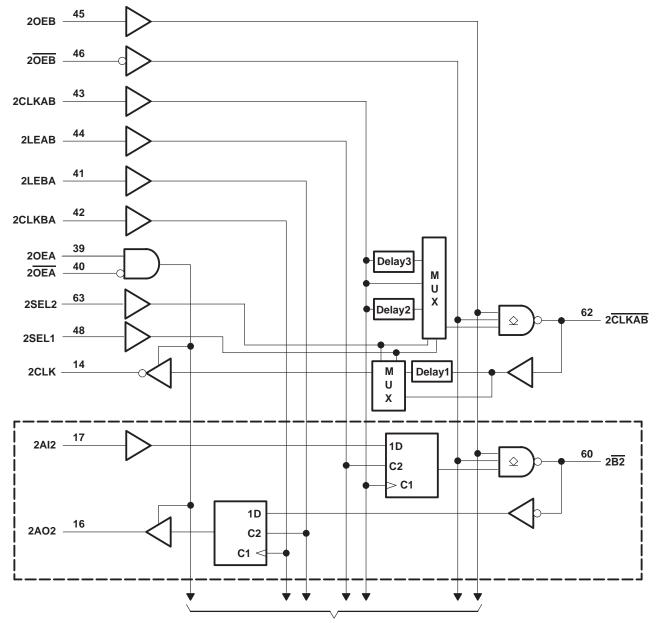
functional block diagram

To Eight Other Channels



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## functional block diagram (continued)



To Seven Other Channels

MUX-MODE DELAY						
INPUTS		DELAY PATH <sup>†</sup>				
2SEL1	2SEL2	2CLKAB TO 2CLKAB	2CLKAB TO 2CLK			
L	L	No delay	No delay			
L	Н	No delay	Delay1			
Н	L	Delay2	Delay1			
Н	Н	Delay3	Delay1			

<sup>†</sup>Refer to delay1 through delay3 in the functional block diagram.



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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range: V <sub>CC</sub> (5 V), BIAS V <sub>CC</sub> , BG V <sub>CC</sub>	
Input voltage range, $V_{I}$ : Except $\overline{B}$ port	
B port	–1.2 V to 3.5 V
Input clamp current, IIK: Except B port	–40 mA
B port	–18 mA
Voltage range applied to any $\overline{B}$ output in the disabled or power-off state	–0.5 V to 3.5 V
Voltage range applied to any output in the high state	–0.5 V to V <sub>CC</sub>
Current applied to any single output in the low state: A port	
	200 mA
Package thermal impedance, $\theta_{JA}$ (see Note 1)	22°C/W
Storage temperature range, T <sub>stg</sub>	

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1: The periods the read the periods are used to be a stress to a stress the periods are used to be a stress.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT	
V <sub>CC,</sub> BG V <sub>CC</sub> , BIAS V <sub>CC</sub>	Supply voltage		4.5	5	5.5	V	
V <sub>CC</sub> (3.3 V)	Supply voltage		3	3.3	3.6	V	
		B port	1.62		2.3		
VIH	High-level input voltage	Except B port	2			V	
		B port	0.75		1.47		
VIL	Low-level input voltage	Except B port			0.8	V	
IK	Input clamp current				-18	mA	
ЮН	High-level output current	AO port			-3	mA	
		AO port			24		
IOL	Low-level output current	B port			100	mA	
T <sub>A</sub>	Operating free-air temperature		0		70	°C	

NOTE 2: To ensure proper device operation, all unused inputs must be terminated as follows: A and control inputs to V<sub>CC</sub>(5 V) or GND, and B inputs to GND only. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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## electrical characteristics over recommended operating free-air temperature range

	PARAMETER	TEST CO	TEST CONDITIONS			UNIT	
	B port	$V_{CC}(5 V) = 4.5 V,$	Ij = –18 mA		-1.2		
VIK	Except B port	V <sub>CC</sub> (3.3 V) = 3.3 V	Ij = -40 mA		-0.5	V	
VOH	AO port	$V_{CC}(5 V) = 4.5 V,$ $V_{CC}(3.3 V) = 3 V$	I <sub>OH</sub> = -3 mA	2.5		V	
	AO port	$V_{CC}(5 V) = 4.5 V,$ $V_{CC}(3.3 V) = 3 V$	I <sub>OL</sub> = 24 mA	0.35	5 0.5		
V <sub>OL</sub>	B port	$V_{CC}(5 V) = 4.5 V,$ $V_{CC}(3.3 V) = 3 V$	I <sub>OL</sub> = 80 mA I <sub>OL</sub> = 100 mA	0.75	1.1 1.15	V	
II	Except B port	V <sub>CC</sub> (5 V) = 5.5 V, V <sub>CC</sub> (3.3 V) = 3.6 V	V <sub>I</sub> = 5.5 V		50	μA	
IIH‡	Except B port	V <sub>CC</sub> (5 V) = 5.5 V, V <sub>CC</sub> (3.3 V) = 3.6 V	V <sub>I</sub> = 2.7 V		50	μA	
. +	Except B port	$\overline{3} \text{ port} \qquad \begin{array}{c} V_{CC}(5 \text{ V}) = 5.5 \text{ V}, \\ V_{CC}(3.3 \text{ V}) = 3.6 \text{ V} \end{array} \qquad \qquad V_{I} = 0.5 \text{ V} \end{array}$		-50			
ι <sub>IL</sub> ‡	B port	$V_{CC}(5 V) = 5.5 V,$ $V_{CC}(3.3 V) = 3.6 V$	V <sub>I</sub> = 0.75 V		-100	μΑ	
ЮН	B port	$V_{CC}(5 V) = 0 \text{ to } 5.5 V,$ $V_{CC}(3.3 V) = 3.6 V$	V <sub>O</sub> = 2.1 V		100	μA	
I <sub>OZH</sub>	AO port	$V_{CC}(5 V) = 5.5 V,$ $V_{CC}(3.3 V) = 3.6 V$	V <sub>O</sub> = 2.7 V		50	μΑ	
I <sub>OZL</sub>	AO port	$V_{CC}(5 V) = 5.5 V,$ $V_{CC}(3.3 V) = 3.6 V$	V <sub>O</sub> = 0.5 V		-50	μΑ	
IOZPU	AO port	$V_{CC} = 0$ to 2.1 V,	$V_{O}$ = 0.5 V to 2.7 V		-50	μΑ	
IOZPD	AO port	$V_{CC} = 2.1 V \text{ to } 0,$	$V_{O}$ = 0.5 V to 2.7 V		-50	μA	
	AI port to B port				145		
ICC(5 V)	B port to AO port	$V_{CC}(5 V) = 5.5 V,$ $V_{CC}(3.3 V) = 3.3 V$	IO = 0		130	mA	
	Outputs disabled				120		
I <sub>CC</sub> (3.3 V)	B port to AO port	$V_{CC}(5 V) = 5.5 V,$ $V_{CC}(3.3 V) = 3.3 V$	I <sub>O</sub> = 0		1	mA	
Ci	Control and AI inputs	VI = 0.5 V or 2.5 V		6.	5	pF	
Co	AO port	$V_{O}$ = 0.5 V or 2.5 V		3.5	5	pF	
C <sub>io</sub>	B port per IEEE Std 1194.1-1991	$V_{CC}(5 V) = 0 \text{ to } 5.5 V,$	V <sub>CC</sub> (3.3 V) = 3.3 V		6.5	pF	

<sup>†</sup> All typical values are at V<sub>CC</sub>(5 V) = 5 V and V<sub>CC</sub>(3.3 V) = 3.3 V, T<sub>A</sub> = 25°C. <sup>‡</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.



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## live-insertion specifications over recommended operating free-air temperature range

PAR	RAMETER	TEST CONDITIONS				MAX	UNIT
		$V_{CC}(5 V) = 0 \text{ to } 4.5 V,$ $V_{CC}(3.3 V) = 3.3 V$	$V_{CC}(3.3 \text{ V}) = 3.3 \text{ V}$			450	•
ICC (R	IAS V <sub>CC</sub> )	$V_{CC}(5 V) = 4.5 V \text{ to } 5.5 V,$ $V_{CC}(3.3 V) = 3.3 V$	$V_B = 0$ to 2 V, $V_I$ (BIAS $V_{CC}$ ) = 4.5 V to 5.5 V			10	μA
VO	B port	$V_{CC}(5 V) = 0,$ $V_{CC}(3.3 V) = 0 V$	$V_{I}$ (BIAS $V_{CC}$ ) = 5 V		1.62	2.1	V
		$V_{CC}(5 V) = 0,$ $V_{CC}(3.3 V) = 0 V$	V <sub>B</sub> = 1 V,	V <sub>I</sub> (BIAS V <sub>CC</sub> ) = 4.5 V to 5.5 V	-1		
IO	B port	$V_{CC}(5 V) = 0 \text{ to } 2.2 V,$ $V_{CC}(3.3 V) = 3.3 V$	OEB = 0 to 5 V			100	μA
		$V_{CC}(5 V) = 0 \text{ to } 5.5 V,$ $V_{CC}(3.3 V) = 3.3 V$	OEB = 0 to 0.8 V			1	mA

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			MIN	MAX	UNIT
fclock	Clock frequency			90	MHz
		LE high	3		
tw	Pulse duration	CLK high or low	3		ns
	Cature time	Al or B before LE↓	3.5		
t <sub>su</sub>	Setup time	AI or B before CLK↑	3.5		ns
4.	Hold time	AI or B after LE↓	1		~~
th	Hold lime	AI or B after CLK↑	0.7		ns



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# switching characteristics over recommended operating free-air temperature range, V\_{CC}(5 V) = 5 V $\pm$ 0.5 V and V\_{CC}(3.3 V) = 3.3 V (see Figure 1)

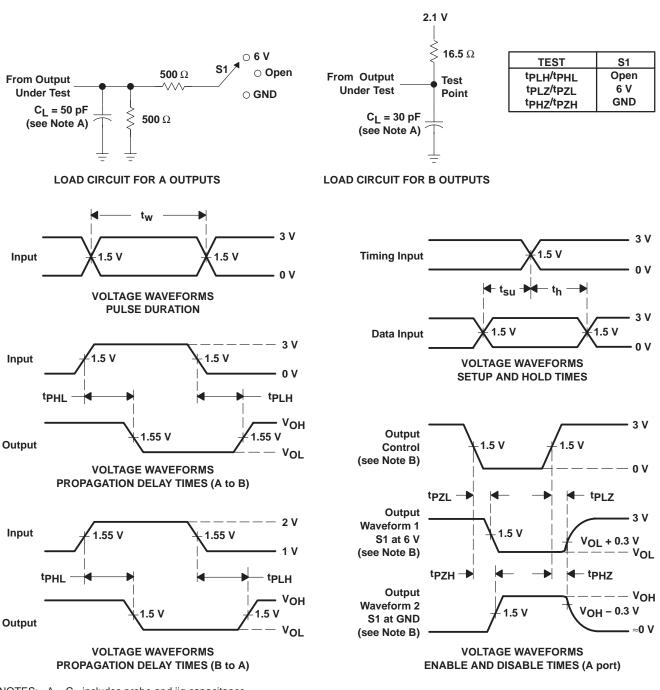
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNI
f <sub>max</sub>			90		MHz
<sup>t</sup> PLH		B	1.8	6.2	
<sup>t</sup> PHL	AI	В	2.9	6.6	ns
<sup>t</sup> PLH	1545	B	2.7	6.9	
<sup>t</sup> PHL	LEAB	В	3.5	7.3	ns
<sup>t</sup> PLH	01//42	В	2.3	6.4	
<sup>t</sup> PHL	CLKAB	В	2.9	6.7	ns
<sup>t</sup> PLH	2CLKAB		2.3	6	
<sup>t</sup> PHL	(no delay)	2CLKAB	2.9	6.7	ns
<sup>t</sup> PLH	2CLKAB		4.5	9.5	
<sup>t</sup> PHL	(delay2)	2CLKAB	4.5	9.5	ns
<sup>t</sup> PLH	2CLKAB		9.3	15.4	
<sup>t</sup> PHL	(delay3)	2CLKAB	9.3	15.4	ns
<sup>t</sup> PLH	=		2	6.5	
<sup>t</sup> PHL	B	AO	2	6.5	ns
<sup>t</sup> PLH			1.8	6.3	
<sup>t</sup> PHL	LEBA	AO	1.8	6.3	ns
<sup>t</sup> PLH			1.8	6.3	
<sup>t</sup> PHL	CLKBA	AO	1.8	6.3	ns
<sup>t</sup> PLH	2CLKAB		5.7	12.3	
<sup>t</sup> PHL	(delay1)	2CLK	5.7	12.3	ns
<sup>t</sup> PLH	2CLKAB		2	6.5	
<sup>t</sup> PHL	(no delay)	2CLK	2	6.5	ns
<sup>t</sup> PLH		B	2.6	7	
<sup>t</sup> PHL	OEB or OEB	В	2.6	7	ns
<sup>t</sup> PZH			1.4	5.5	
<sup>t</sup> PZL	OEA or OEA	AO	1.4	5.5	ns
<sup>t</sup> PHZ			1.4	6.5	
<sup>t</sup> PLZ	OEA or OEA	AO	1.4	5.8	ns
	Pulse skew, AI to B or B to AO			1.6	
<sup>t</sup> sk(p) <sup>†</sup>	Pulse skew, 2CLKAB to 2CLK			1.8	ns
	Pulse skew, CLKAB to B or CLKBA to A	λO		1.5	
<sup>t</sup> sk(p)	Pulse skew, CLKAB to 2CLKAB			1.4	ns
<sup>t</sup> sk(HL) <sup>, t</sup> sk(LH) <sup>†</sup>	Output skew, AI to B or B to AO				
	Output skew, nondelayed mode for 2CL	KAB, CLKAB to AO		1	
<sup>t</sup> sk(o) <sup>‡</sup>	Output skew, nondelayed mode for 2CL	KAB, CLKAB to B and 2CLKAB		1	ns
t <sub>sk(o)</sub> ‡	Output skew, nondelayed mode for 2CL	Output skew, nondelayed mode for 2CLKAB, CLKAB to B and 2CLKAB			
	Transition time, $\overline{B}$ outputs (1.3 V to 1.8		0.5	4.6	
tt	Transition time, AO outputs (10% to 90%				
<sup>t</sup> PR	B-port input pulse rejection		0.4	4.2	ns

<sup>†</sup> Skew values are applicable for through mode only, with single-output switching.

\$\$ Skew values are applicable for CLK mode only, with all outputs simultaneously switching high-to-low or low-to-high.



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
   C. All input pulses are supplied by generators having the following characteristics: TTL inputs: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> ≤ 2.5 ns,
- $t_f \le 2.5$  ns; BTL inputs: PRR  $\le 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_f \le 1$  ns,  $t_f \le 1$  ns.
- D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins I	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74FB1653PCA	ACTIVE	HLQFP	PCA	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
SN74FB1653PCAG4	ACTIVE	HLQFP	PCA	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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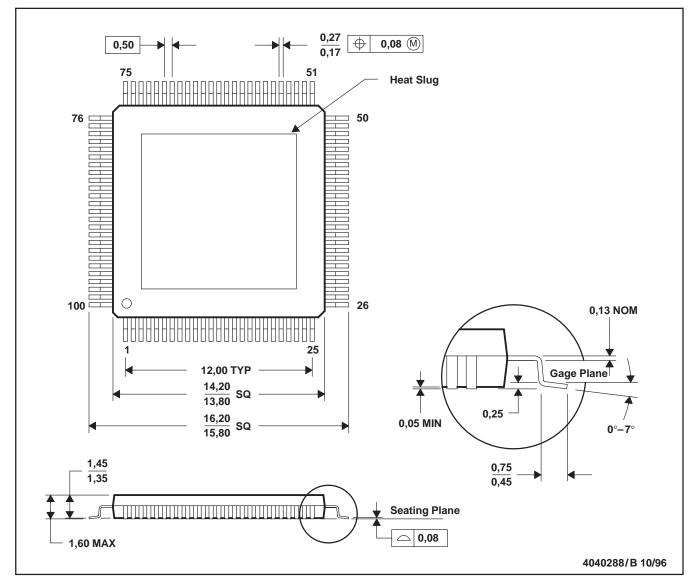
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# **MECHANICAL DATA**

MHTQ003A - JANUARY 1995 - REVISED DECEMBER 1996

#### PCA (S-PQFP-G100)

#### PLASTIC QUAD FLATPACK (DIE DOWN)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Thermally enhanced molded plastic package with a heat slug (HSL)
- D. Falls within JEDEC MS-026



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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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